

# DATA SHEET



BITSTREAM CONVERSION

## **UDA1350ATS** **IEC 60958 audio DAC**

Product specification  
Supersedes data of 2000 Mar 29  
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2001 Mar 27

**IEC 60958 audio DAC****UDA1350ATS**

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**1 FEATURES****1.1 General**

- 2.7 to 3.6 V power supply
- Integrated digital filter and Digital-to-Analog Converter (DAC)
- $256f_s$  system clock output
- 20-bit data path in interpolator
- High performance
- No analog post filtering required for DAC.

**1.2 Control**

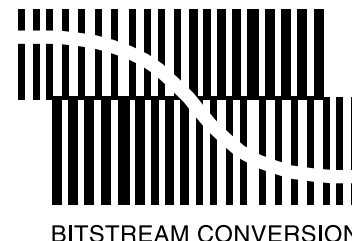
- Controlled either by means of static pins or via the L3 microcontroller interface.

**1.3 IEC 60958 input**

- On-chip amplifier for converting IEC 60958 input to CMOS levels
- Lock indication signal available on pin LOCK
- Lock indication signal combined on-chip with the Pulse Code Modulation (PCM) status bit; in case non-PCM has been detected pin LOCK indicates out-of-lock
- Key channel-status bits available via L3 interface (lock, pre-emphasis, audio sample frequency, two channel PCM indication and clock accuracy).

**1.4 Digital sound processing and DAC**

- Automatic de-emphasis when using IEC 60958 input with 32.0, 44.1 and 48.0 kHz audio sample frequencies
- Soft mute by means of a cosine roll-off circuit selectable via pin MUTE or the L3 interface
- dB linear volume control with 1 dB steps from 0 dB to  $-60$  dB and  $-\infty$  dB
- Bass boost and treble control in L3 control mode
- Interpolating filter ( $f_s$  to  $128f_s$ ) by means of a cascade of a recursive filter and a FIR filter
- Third order noise shaper operating at  $128f_s$  generates the bitstream for the DAC
- Filter stream digital-to-analog converter.

**2 APPLICATIONS**

- Digital audio systems.

**3 GENERAL DESCRIPTION**

Available in two versions:

- UDA1350ATS:
  - only IEC 60958 input to DAC in SSOP28 package.
- UDA1350AH:
  - full featured version in QFP44 package.

The UDA1350ATS is a single chip IEC 60958 audio decoder with an integrated stereo digital-to-analog converter employing bitstream conversion techniques.

A lock indication signal is available on pin LOCK indicating that the IEC 60958 decoder is locked. This pin is also used to indicate whether PCM data is applied to the input or not. In the event non-PCM data has been detected, the device indicates out-of-lock.

By default the DAC output and the data output interface are muted when the decoder is out-of-lock. However, this setting can be overruled in the L3 control mode.

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## 4 QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Supplies</b>						
$V_{DDD}$	digital supply voltage		2.7	3.0	3.6	V
$V_{DDA}$	analog supply voltage		2.7	3.0	3.6	V
$I_{DDA(DAC)}$	analog supply current of DAC	power-on	–	8.0	–	mA
		power-down	–	750	–	$\mu$ A
$I_{DDA(PLL)}$	analog supply current of PLL		–	0.7	–	mA
$I_{DDD}$	digital supply current		–	2.0	–	mA
$I_{DDD(C)}$	digital supply current of core		–	16.0	–	mA
P	power consumption	DAC in playback mode	–	80	–	mW
		DAC in Power-down mode	–	58	–	mW
<b>General</b>						
$t_{rst}$	reset active time		–	250	–	$\mu$ s
$T_{amb}$	ambient temperature		–40	–	+85	$^{\circ}$ C
<b>Digital-to-Analog Converter</b>						
$V_{o(rms)}$	output voltage (RMS value)	note 1	–	900	–	mV
(THD + N)/S	total harmonic distortion-plus-noise to signal ratio	$f_i = 1.0$ kHz tone at 0 dB	–	–90	–85	dB
		at –40 dB; A-weighted	–	–60	–55	dB
S/N	signal-to-noise ratio	$f_i = 1.0$ kHz tone; code = 0; A-weighted	95	100	–	dB
$\alpha_{cs}$	channel separation	$f_i = 1.0$ kHz tone	–	96	–	dB
$\Delta V_o$	unbalance of output voltages	$f_i = 1.0$ kHz tone	–	0.1	0.4	dB

**Note**

1. The output voltage of the DAC is proportional to the DAC power supply voltage.

## 5 ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
UDA1350ATS	SSOP28	plastic shrink small outline package; 28 leads	SOT341-1

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6 BLOCK DIAGRAM

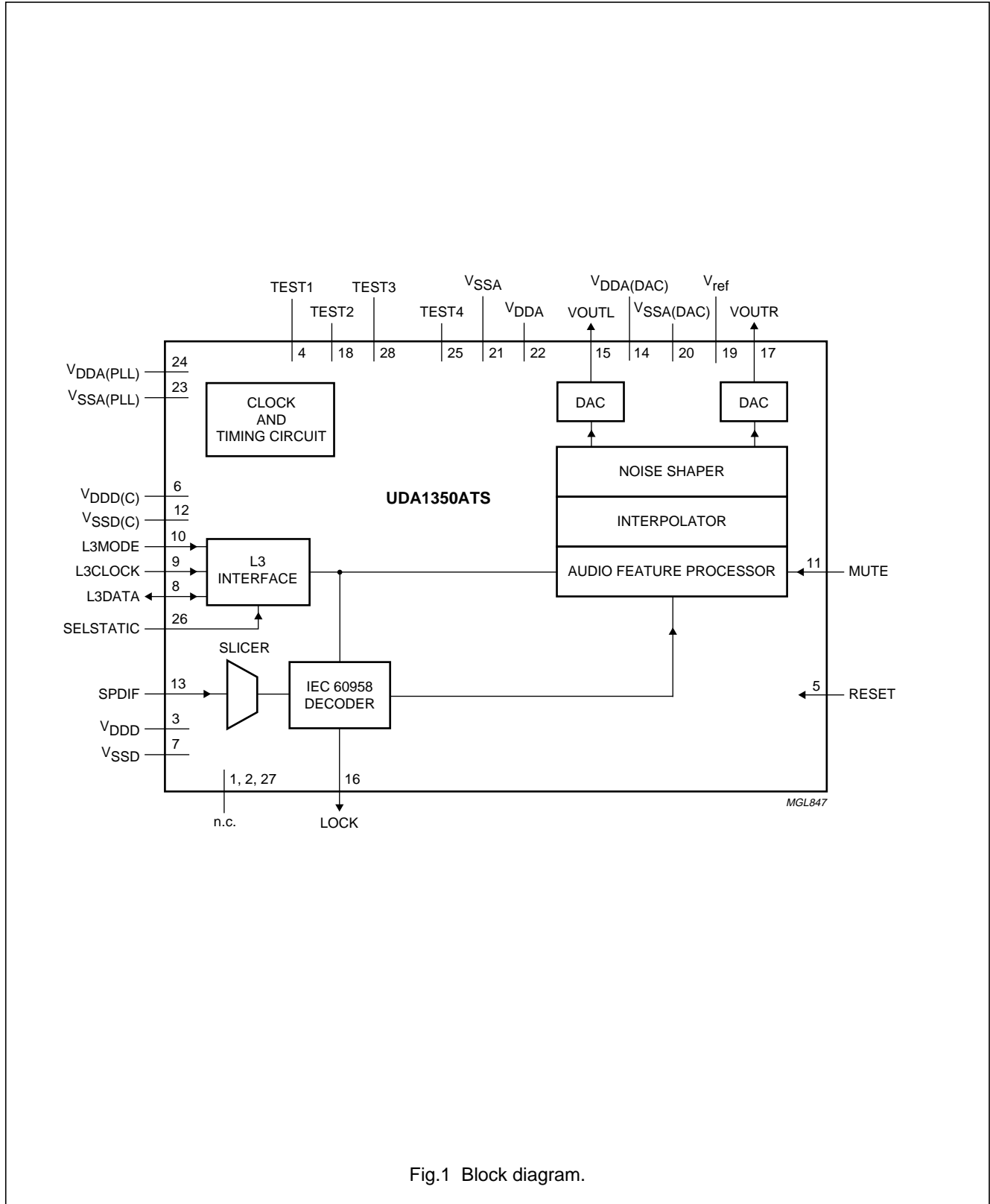


Fig.1 Block diagram.

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## 7 PINNING

SYMBOL	PIN	TYPE <sup>(1)</sup>	DESCRIPTION
n.c.	1	–	not connected
n.c.	2	–	not connected
V <sub>DDD</sub>	3	DS	digital supply voltage
TEST1	4	DID	test pin 1; must be connected to digital ground (V <sub>SSD</sub> )
RESET	5	DISD	reset input
V <sub>DDD(C)</sub>	6	DS	digital supply voltage for core
V <sub>SSD</sub>	7	DGND	digital ground
L3DATA	8	DIOS	L3 interface data input and output
L3CLOCK	9	DIS	L3 interface clock input
L3MODE	10	DIS	L3 interface mode input
MUTE	11	DID	mute control input
V <sub>SSD(C)</sub>	12	DGND	digital ground for core
SPDIF	13	AI	IEC 60958 channel input
V <sub>D(DAC)</sub>	14	AS	analog supply voltage for DAC
VOU <sub>TL</sub>	15	AO	analog DAC left channel output
LOCK	16	DO	SPDIF and PLL lock indicator output
VOU <sub>TR</sub>	17	AO	analog DAC right channel output
TEST2	18	DID	test pin 2; must be connected to digital ground (V <sub>SSD</sub> )
V <sub>ref</sub>	19	A	DAC reference voltage
V <sub>SSA(DAC)</sub>	20	AGND	analog ground for DAC
V <sub>SSA</sub>	21	AGND	analog ground
V <sub>D(DA)</sub>	22	AS	analog supply voltage
V <sub>SSA(PLL)</sub>	23	AGND	analog ground for PLL
V <sub>D(DA(PLL))</sub>	24	AS	analog supply voltage for PLL
TEST4	25	DIU	test pin 4; must be connected to the digital supply voltage (V <sub>DDD</sub> )
SELSTATIC	26	DIU	static pin control selection input
n.c.	27	–	not connected
TEST3	28	DISD	test pin 3; must be connected to digital ground (V <sub>SSD</sub> )

**Note**

1. See Table 1.

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**Table 1** Pin type references

PIN TYPE	DESCRIPTION
DS	digital supply
DGND	digital ground
AS	analog supply
AGND	analog ground
DI	digital input
DIS	digital Schmitt-triggered input
DID	digital input with internal pull-down resistor
DISD	digital Schmitt-triggered input with internal pull-down resistor
DIU	digital input with internal pull-up resistor
DO	digital output
DIO	digital input and output
DIOS	digital Schmitt-triggered input and output
A	analog reference voltage
AI	analog input
AO	analog output

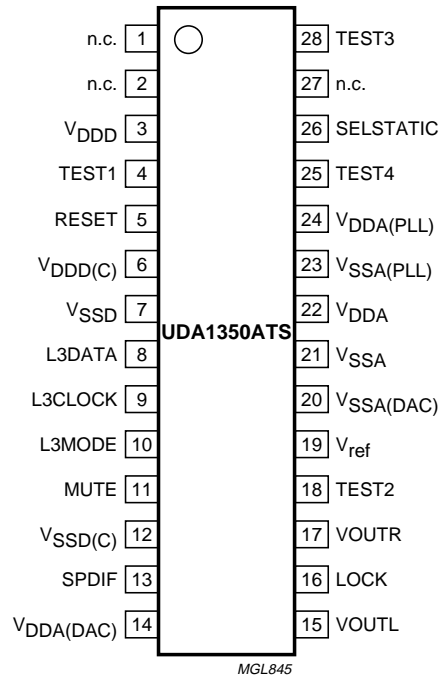


Fig.2 Pin configuration.

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## 8 FUNCTIONAL DESCRIPTION

The UDA1350ATS is a low cost audio IEC 60958 decoder with an on-board DAC. The minimum audio input sampling frequency conforming to the IEC60958 standard is 28.0 kHz and the maximum audio sampling frequency is 54.0 kHz.

### 8.1 Clock regeneration and lock detection

The UDA1350ATS contains an on-board PLL for regenerating a system clock from the IEC 60958 input bitstream.

**Note:** If there is no input signal, the PLL generates a minimum frequency and the output spectrum shifts accordingly. Since the analog output does not have an analog mute, this means noise that is out of band under normal conditions can move into the audio band.

When the on-board clock has locked to the incoming frequency, the lock indicator bit will be set and can be read via the L3 interface. Internally, the PLL lock indication is combined with the PCM status bit of the input data stream. When both the IEC 60958 decoder and the on-board clock have locked to the incoming signal and the input data stream is PCM data, pin LOCK will be asserted. However, when the IC is locked but the PCM status bit reports non-PCM data, pin LOCK is returned to LOW level.

The lock indication output can be used, for example, for muting purposes. The lock signal can be used to drive an external analog muting circuit to prevent out of band noise from becoming audible when the PLL runs at its minimum frequency (e.g. when there is no SPDIF input signal).

An example of the mute circuit is illustrated in Fig.3 where  $V_{DD}$  is the positive power supply and  $V_{SS}$  is the negative power supply.

### 8.2 Mute

The UDA1350ATS is equipped with a cosine roll-off mute in the DSP data path of the DAC part. Muting the DAC, by pin MUTE (in static mode) or via bit MT (in L3 mode) will result in a soft mute as presented in Fig.4. The cosine roll-off soft mute takes  $32 \times 32$  samples = 24 ms at 44.1 kHz sampling frequency.

When operating in the L3 control mode the device will mute on start-up. In L3 mode it is necessary to explicitly switch off the mute for audio output by means of the MT bit in the L3 register.

In the L3 mode pin MUTE does not have any function (the same holds for several other pins) and can either be left open-circuit (since it has an internal pull-down resistor) or be connected to ground.

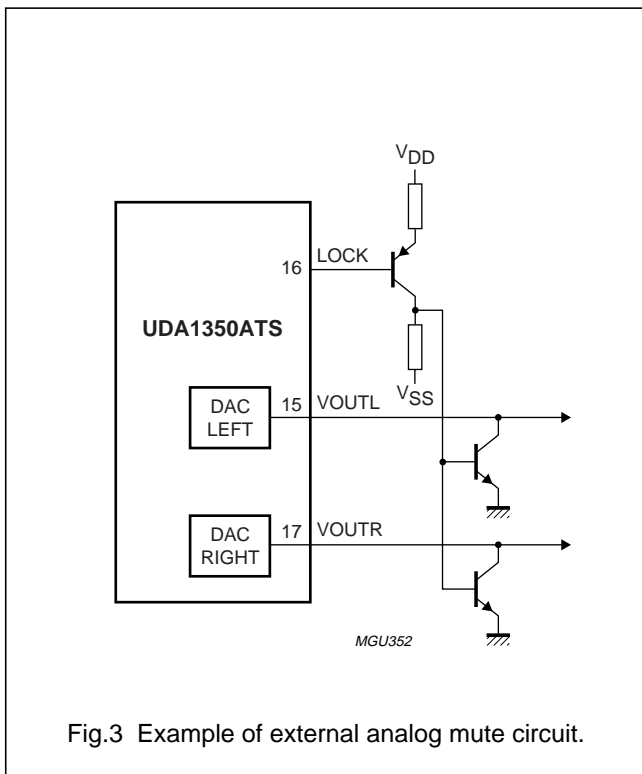


Fig.3 Example of external analog mute circuit.

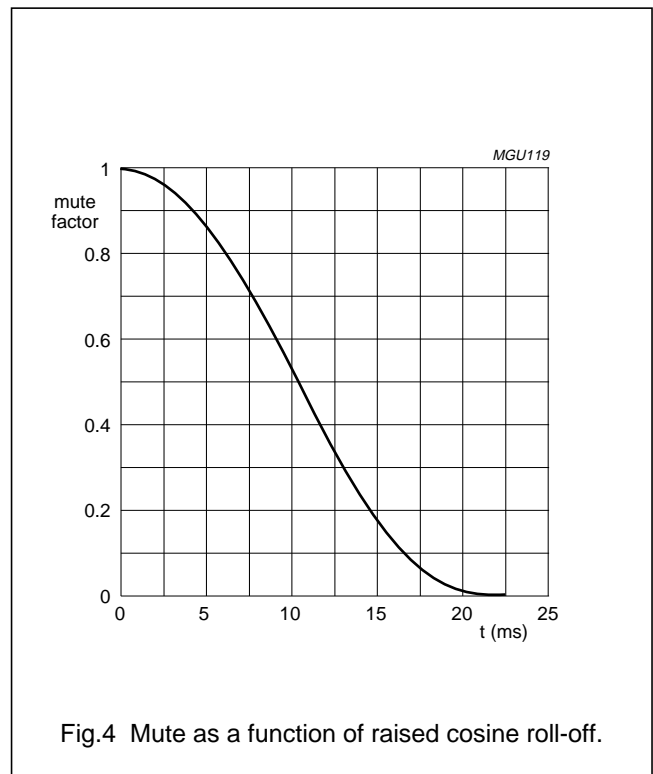


Fig.4 Mute as a function of raised cosine roll-off.



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8.3 Auto mute

By default the outputs of the digital data output interface and the DAC will be muted until the IC is locked, regardless the level on pin MUTE (in static mode) or the state of bit MT of the sound feature register (in L3 mode). In this way only valid data will be passed to the outputs. This mute is done in the SPDIF interface and is a hard mute, not a cosine roll-off mute.

If needed this muting can be bypassed by setting bit AutoMT to logic 0 via the L3 interface. As a result the IC will no longer mute during out-of-lock situations.

8.4 Data path

The UDA1350ATS data path consists of the IEC 60958 decoder, the audio feature processor, digital interpolator and noise shaper and the digital-to-analog converters.

8.4.1 IEC 60958 INPUT

The UDA1350ATS IEC 60958 decoder features an on-chip amplifier with hysteresis which amplifies the IEC 60958 input signal to CMOS level (see Fig.5).

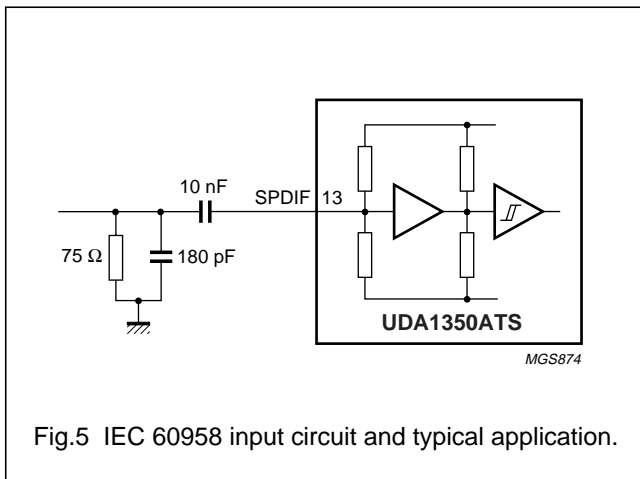


Fig.5 IEC 60958 input circuit and typical application.

All 24 bits of data for left and right are extracted from the input bitstream as well as several of the IEC 60958 key channel-status bits.

The extracted key parameters are:

- Pre-emphasis
- Audio sample frequency
- Two-channel PCM indicator
- Clock accuracy.

Both the lock indicator and the key channel status bits are accessible via the L3 interface.

The UDA1350ATS supports the following sample frequencies and data bit rates:

- $f_s = 32.0$  kHz, resulting in a data rate of 2.048 Mbits/s
- $f_s = 44.1$  kHz, resulting in a data rate of 2.8224 Mbits/s
- $f_s = 48.0$  kHz, resulting in a data rate of 3.072 Mbits/s.

The UDA1350ATS supports timing level I, II and III as specified by the IEC 60958 standard.

8.4.2 AUDIO FEATURE PROCESSOR

The audio feature processor automatically provides de-emphasis for the IEC 60958 data stream in the static pin control mode and default mute at start-up in the L3 control mode.

When used in the L3 control mode it provides the following additional features:

- Volume control using 6 bits
- Bass boost control using 4 bits
- Treble control using 2 bits
- Mode selection of the sound processing bass boost and treble filters: flat, minimum and maximum
- Soft mute control with raised cosine roll-off
- De-emphasis selection of the incoming data stream for  $f_s = 32.0, 44.1$  and  $48.0$  kHz.

8.4.3 INTERPOLATOR

The UDA1350ATS includes an on-board interpolating filter which converts the incoming data stream from  $1f_s$  to  $128f_s$  by cascading a recursive filter and a FIR filter.

Table 2 Interpolator characteristics

PARAMETER	CONDITIONS	VALUE (dB)
Pass-band ripple	0 to $0.45f_s$	$\pm 0.03$
Stop band	$>0.65f_s$	-50
Dynamic range	0 to $0.45f_s$	115
DC gain	-	-3.5

8.4.4 NOISE SHAPER

The third-order noise shaper operates at  $128f_s$ . It shifts in-band quantization noise to frequencies well above the audio band. This noise shaping technique enables high signal-to-noise ratios to be achieved. The noise shaper output is converted into an analog signal using a filter stream digital-to-analog converter.

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## 8.4.5 FILTER STREAM DAC

The Filter Stream DAC (FSDAC) is a semi-digital reconstruction filter that converts the 1-bit data stream of the noise shaper to an analog output voltage. The filter coefficients are implemented as current sources and are summed at virtual ground of the output operational amplifier. In this way very high signal-to-noise performance and low clock jitter sensitivity is achieved. A post filter is not needed due to the inherent filter function of the DAC. On-board amplifiers convert the FSDAC output current to an output voltage signal capable of driving a line output.

The output voltage of the FSDAC is scaled proportionally with the power supply voltage.

## 8.5 Control

The UDA1350ATS can be controlled by means of static pins or via the L3 interface. For optimum use of the features of the UDA1350ATS the L3 control mode is recommended since only basic functions are available in the static pin control mode.

It should be noted that the static pin control mode and L3 control mode are mutual exclusive. In the static pin control mode pins L3MODE and L3DATA are used to select the format for the data output and input interface.

## 8.5.1 STATIC PIN CONTROL MODE

The default values for all non-pin controlled settings are identical to the default values at start-up in the L3 control mode.

**Table 3** Pin description of static pin control mode

PIN	NAME	VALUE	FUNCTION
<b>Mode selection pin</b>			
26	SELSTATIC	1	select static pin control mode; must be connected to $V_{DD}$
<b>Input pins</b>			
5	RESET	0	normal operation
		1	reset
8	L3DATA	0	must be connected to $V_{SSD}$
9	L3CLOCK	0	must be connected to $V_{SSD}$
10	L3MODE	0	must be connected to $V_{SSD}$
11	MUTE	0	normal operation
		1	mute active
<b>Status pins</b>			
16	LOCK	0	clock regeneration and IEC 60958 decoder out-of-lock <b>or</b> non-PCM data detected
		1	clock regeneration and IEC 60958 decoder locked <b>and</b> PCM data detected
<b>Test pins</b>			
4	TEST1	0	must be connected to digital ground ( $V_{SSD}$ )
18	TEST2	0	must be connected to digital ground ( $V_{SSD}$ )
25	TEST4	1	must be connected to digital supply voltage ( $V_{DD}$ )
28	TEST3	0	must be connected to digital ground ( $V_{SSD}$ )

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## 8.5.2 L3 CONTROL MODE

The L3 control mode allows maximum flexibility in controlling the UDA1350ATS.

It should be noted that in the L3 control mode several base-line functions are still controlled by pins on the device and that on start-up in the L3 control mode the output is explicitly muted by bit MT via the L3 interface.

**Table 4** Pin description in the L3 control mode

PIN	NAME	VALUE	FUNCTION
<b>Mode selection pin</b>			
26	SELSTATIC	0	select L3 control mode; must be connected to $V_{SSD}$
<b>Input pins</b>			
5	RESET	0	normal operation
		1	reset
8	L3DATA	–	must be connected to the L3-bus
9	L3CLOCK	–	must be connected to the L3-bus
10	L3MODE	–	must be connected to the L3-bus
<b>Status pins</b>			
16	LOCK	0	clock regeneration and IEC 60958 decoder out-of-lock <b>or</b> non-PCM data detected
		1	clock regeneration and IEC 60958 decoder locked <b>and</b> PCM data detected
<b>Test pins</b>			
4	TEST1	0	must be connected to ground ( $V_{SSD}$ )
18	TEST2	0	must be connected to ground ( $V_{SSD}$ )
25	TEST4	1	must be connected to digital supply voltage ( $V_{DDD}$ )
28	TEST3	0	must be connected to ground ( $V_{SSD}$ )

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**8.6 L3 interface****8.6.1 GENERAL**

The UDA1350ATS has an L3 microcontroller interface and all the digital sound processing features and various system settings can be controlled by a microcontroller.

The controllable settings are:

- Restoring L3 defaults
- Power-on
- Selection of filter mode and settings of treble and bass boost
- Volume settings
- Selection of soft mute via cosine roll-off and bypass of auto mute
- Selection of de-emphasis (only effective in L3 control mode).

The readable settings are:

- Mute status of interpolator
- PLL locked
- SPDIF input signal locked
- Audio Sample Frequency (ASF)
- Valid PCM data detected
- Pre-emphasis of the IEC 60958 input signal
- ACcuracy of the Clock (ACC).

The exchange of data and control information between the microcontroller and the UDA1350ATS is accomplished through a serial hardware L3 interface comprising the following pins:

- L3DATA: data line
- L3MODE: mode line
- L3CLK: clock line.

The exchange of bytes via the L3 interface is LSB first.

The L3 format has two modes of operation:

- Address mode
- Data transfer mode.

The address mode is used to select a device for a subsequent data transfer. The address mode is characterized by L3MODE being LOW and a burst of 8 pulses on L3CLOCK, accompanied by 8 bits (see Fig.6). The data transfer mode is characterized by L3MODE being HIGH and is used to transfer one or more bytes representing a register address, instruction or data.

Basically two types of data transfers can be defined:

- Write action: data transfer **to** the device
- Read action: data transfer **from** the device.

**Remark:** when the device is powered up, at least one L3CLOCK pulse must be given to the L3 interface to wake-up the interface before starting sending to the device (see Fig.6). This is only needed once after the device is powered up.

**8.6.2 DEVICE ADDRESSING**

The device address consists of one byte with:

- Data Operating Mode (DOM) bits 0 and 1 representing the type of data transfer (see Table 5)
- Address bits 2 to 7 representing a 6-bit device address.

**Table 5** Selection of data transfer

DOM		TRANSFER
BIT 0	BIT 1	
0	0	not used
1	0	not used
0	1	write data or prepare read
1	1	read data

**8.6.3 REGISTER ADDRESSING**

After sending the device address, including DOM bits indicating whether the information is to be read or written, one data byte is sent using bit 0 to indicate whether the information will be read or written and bits 1 to 7 for the destination register address.

Basically there are three methods for register addressing:

1. Addressing for write data: bit 0 is logic 0 indicating a write action to the destination register, followed by bits 1 to 7 indicating the register address (see Fig.6).
2. Addressing for prepare read: bit 0 is logic 1 indicating that data will be read from the register (see Fig.7).
3. Addressing for data read action: in this case the device returns a register address prior to sending data from that register. When bit 0 is logic 0, the register address is valid; in case bit 0 is logic 1 the register address is invalid.

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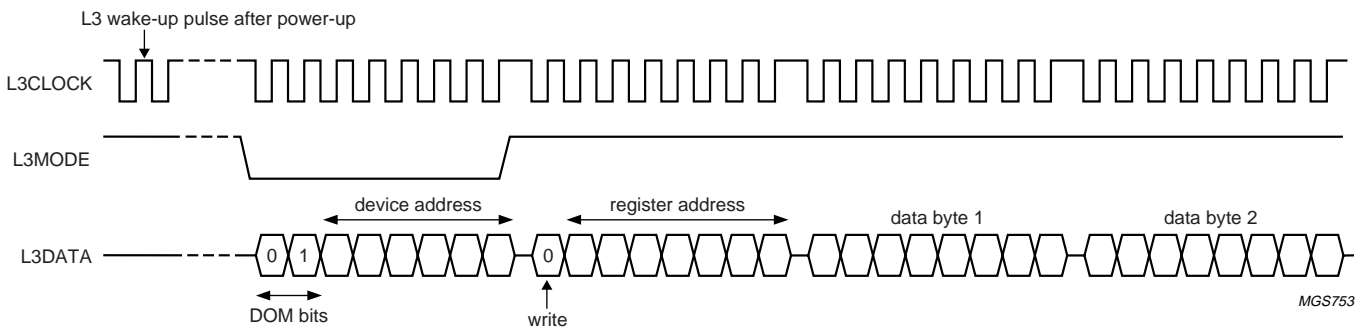


Fig.6 Data write mode (for L3 version 2).

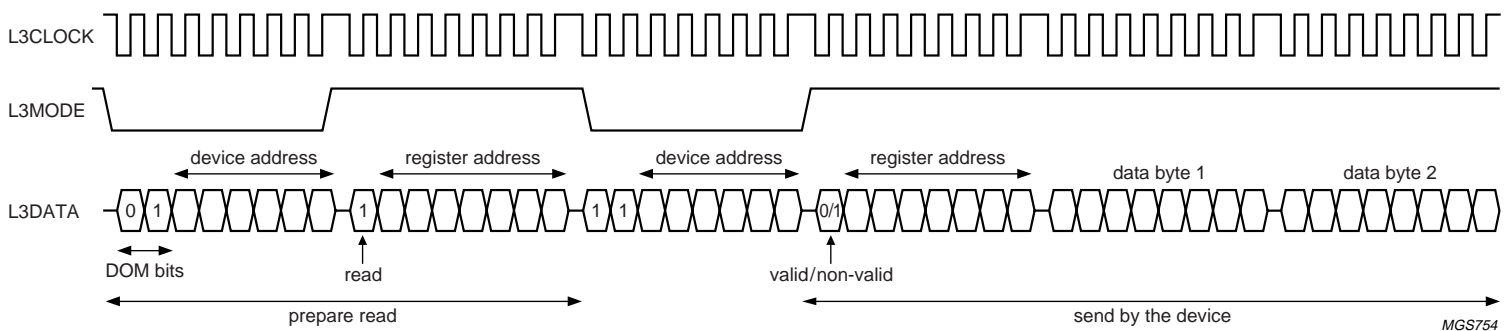


Fig.7 Data read mode.

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## 8.6.4 DATA WRITE MODE

The data write mode is explained in the signal diagram of Fig.6. For writing data to a device, four bytes must be sent (see Table 6):

1. One byte starting with '01' for signalling the write action to the device, followed by the device address ('011000' for the UDA1350ATS).
2. One byte starting with a '0' for signalling the write action, followed by 7 bits indicating the destination address in binary format with A6 being the MSB and A0 being the LSB.
3. Two data bytes with D15 being the MSB and D0 being the LSB.

It should be noted that each time a new destination register address needs to be written, the device address must be sent again.

## 8.6.5 DATA READ MODE

For reading data from the device, first a prepare read must be done and then data read. The data read mode is explained in the signal diagram of Fig.7.

For reading data from a device, the following six bytes are involved (see Table 7):

1. One byte with the device address including '01' for signalling the write action to the device.
2. One byte is sent with the register address from which data needs to be read. This byte starts with a '1', which indicates that there will be a read action from the register, followed again by 7 bits for the destination address in binary format with A6 being the MSB and A0 being the LSB.
3. One byte with the device address including '11' is sent to the device. The '11' indicates that the device must write data to the microcontroller.
4. One byte, sent by the device to the bus, with the (requested) register address and a flag bit indicating whether the requested register was valid (bit is logic 0) or invalid (bit is logic 1).
5. Two bytes, sent by the device to the bus, with the data information in binary format with D15 being the MSB and D0 being the LSB.

Table 6 L3 write data

BYTE	L3 MODE	ACTION	FIRST IN TIME				LATEST IN TIME			
			BIT 0	BIT 1	BIT 2	BIT 3	BIT 4	BIT 5	BIT 6	BIT 7
1	address	device address	0	1	0	1	1	0	0	0
2	data transfer	register address	0	A6	A5	A4	A3	A2	A1	A0
3	data transfer	data byte 1	D15	D14	D13	D12	D11	D10	D9	D8
4	data transfer	data byte 2	D7	D6	D5	D4	D3	D2	D1	D0

Table 7 L3 read data

BYTE	L3 MODE	ACTION	FIRST IN TIME				LATEST IN TIME			
			BIT 0	BIT 1	BIT 2	BIT 3	BIT 4	BIT 5	BIT 6	BIT 7
1	address	device address	0	1	0	1	1	0	0	0
2	data transfer	register address	1	A6	A5	A4	A3	A2	A1	A0
3	address	device address	1	1	0	1	1	0	0	0
4	data transfer	register address	0 or 1	A6	A5	A4	A3	A2	A1	A0
5	data transfer	data byte 1	D15	D14	D13	D12	D11	D10	D9	D8
6	data transfer	data byte 2	D7	D6	D5	D4	D3	D2	D1	D0

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## 8.6.6 INITIALISATION STRING

For proper and reliable operation it is needed that the UDA1350ATS is initialized in the L3 control mode. This is needed to have the PLL start up after powering up of the device under all conditions. The initialisation string is given in Table 8.

**Table 8** L3 init string and set defaults after power-up.

BYTE	L3 MODE	ACTION		FIRST IN TIME					LATEST IN TIME		
				BIT 0	BIT 1	BIT 2	BIT 3	BIT 4	BIT 5	BIT 6	BIT 7
1	address	init string	device address	0	1	0	1	1	0	0	0
2	data transfer		register address	0	1	0	0	0	0	0	0
3	data transfer		data byte 1	0	0	0	0	0	0	0	0
4	data transfer		data byte 2	0	0	0	0	0	0	1	1
5	address	set defaults	device address	0	1	0	1	1	0	0	0
6	data transfer		register address	0	1	1	1	1	1	1	1
7	data transfer		data byte 1	0	0	0	0	0	0	0	0
8	data transfer		data byte 2	0	0	0	0	0	0	0	0

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## 8.6.7 OVERVIEW OF L3 INTERFACE REGISTERS

**Table 9** UDA1350ATS register map

ADDR	FUNCTION	BIT															
		D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
<b>Writable settings</b>																	
00H	system parameters			PON													
	default			1			0 <sup>(1)</sup>	0 <sup>(1)</sup>			1 <sup>(2)</sup>		0 <sup>(1)</sup>	0 <sup>(1)</sup>			
10H	sound features			M1	M0	BB3	BB2	BB1	BB0				TR1	TR0	DE1	DE0	MT
	default			0	0	0	0	0	0				0	0	0	0	1
11H	volume control DAC											VC5	VC4	VC3	VC2	VC1	VC0
	default											0	0	0	0	0	0
40H	multiplex parameters															Auto MT	RST PLL
	default											0 <sup>(1)</sup>	0 <sup>(1)</sup>	0 <sup>(1)</sup>	0 <sup>(1)</sup>	1	
7FH	restore L3 defaults																
<b>Readable settings</b>																	
18H	interpolator parameters																MT stat
38H	SPDIF input and lock parameters						PLL lock		SPD lock	ASF1	ASF0	PCM stat		PRE		ACC1	ACC0

**Notes**

1. When writing new settings via the L3 interface, these bits should always remain logic 0 (default value) to warrant correct operation.
2. When writing new settings via the L3 interface, these bits should always remain logic 1 (default value) to warrant correct operation.



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## 8.6.8 WRITABLE REGISTERS

## 8.6.8.1 Restoring L3 defaults

By writing to the 7FH register, all L3 control values are restored to their default values. Only the L3 interface is affected, the system will not be reset. Consequently readable registers, which are not reset, can be affected.

## 8.6.8.2 Power-on

A 1-bit value to switch the DAC on and off.

Table 10 Power-on setting

PON	FUNCTION
0	power-down
1	power-on (default setting)

## 8.6.8.3 Filter mode selection

A 2-bit value to program the mode for the sound processing filters of bass boost and treble.

Table 11 Filter mode settings

M1	M0	FUNCTION
0	0	flat (default setting)
0	1	minimum
1	0	
1	1	maximum

## 8.6.8.4 Treble

A 2-bit value to program the treble setting in combination with the filter mode settings. At  $f_s = 44.1$  kHz the  $-3$  dB point for minimum setting is 3.0 kHz and the  $-3$  dB point for maximum setting is 1.5 kHz. The default value is '00'.

Table 12 Treble settings

TR1	TR0	LEVEL (dB)		
		FLAT	MIN.	MAX.
0	0	0	0	0
0	1	0	2	2
1	0	0	4	4
1	1	0	6	6

## 8.6.8.5 Bass boost

A 4-bit value to program the bass boost setting in combination with the filter mode settings. At  $f_s = 44.1$  kHz the  $-3$  dB point for minimum setting is 250 Hz and the  $-3$  dB point for maximum setting is 300 Hz. The default value is '0000'.

Table 13 Bass boost settings

BB3	BB2	BB1	BB0	LEVEL (dB)		
				FLAT	MIN.	MAX.
0	0	0	0	0	0	0
0	0	0	1	0	2	2
0	0	1	0	0	4	4
0	0	1	1	0	6	6
0	1	0	0	0	8	8
0	1	0	1	0	10	10
0	1	1	0	0	12	12
0	1	1	1	0	14	14
1	0	0	0	0	16	16
1	0	0	1	0	18	18
1	0	1	0	0	18	20
1	0	1	1	0	18	22
1	1	0	0	0	18	24
1	1	0	1	0	18	24
1	1	1	0	0	18	24
1	1	1	1	0	18	24

## 8.6.8.6 De-emphasis

A 2-bit value to enable the digital de-emphasis filter.

Table 14 De-emphasis selection

DE1	DE0	FUNCTION
0	0	other (default setting)
0	1	$f_s = 32.0$ kHz
1	0	$f_s = 44.1$ kHz
1	1	$f_s = 48.0$ kHz

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**8.6.8.7** *Soft mute*

A 1-bit value to enable the digital mute.

**Table 15** Soft mute selection

MT	FUNCTION
0	no muting
1	muting (default setting)

**8.6.8.8** *Volume control*

A 6-bit value to program the left and right channel volume attenuation. The range is from 0 to  $-\infty$  dB in steps of 1 dB.

**Table 16** Volume settings of the interpolator

VC5	VC4	VC3	VC2	VC1	VC0	VOLUME (dB)
0	0	0	0	0	0	0
0	0	0	0	0	1	0
0	0	0	0	1	0	-1
0	0	0	0	1	1	-2
:	:	:	:	:	:	:
1	1	1	0	1	1	-58
1	1	1	1	0	0	-59
1	1	1	1	0	1	-60
1	1	1	1	1	0	$-\infty$
1	1	1	1	1	1	$-\infty$

**8.6.8.9** *Auto mute*

A 1-bit value to activate mute during out-of-lock. In normal operation the output is automatically hard muted when an out-of-lock situation is detected. Setting this bit to logic 0 will disable that function.

**Table 17** Auto mute setting

Auto MT	FUNCTION
0	do not mute output during out-of-lock
1	mute output during out-of-lock (default setting)

**8.6.8.10** *PLL reset*

A 1-bit value to reset the PLL. This is the bit which is set in the initialisation string. When this bit is asserted, the PLL will be reset and the output clock of the PLL will be forced to its lowest value, which is in the area of a few MHz.

**Table 18** PLL reset

RST PLL	FUNCTION
0	normal operation
1	PLL is reset

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## 8.6.9 READABLE REGISTERS

## 8.6.9.1 Mute status

A 1-bit value indicating whether the interpolator is muting or not muting.

**Table 19** Interpolator mute status

MT stat	FUNCTION
0	no muting
1	muting

## 8.6.9.2 PLL lock detection

A 1-bit value indicating that the clock regeneration is locked.

**Table 20** PLL lock indication

PLL lock	FUNCTION
0	out-of-lock
1	locked

## 8.6.9.3 SPDIF lock detection

A 1-bit value indicating the IEC 60958 decoder is locked and is decoding correct data.

**Table 21** SPDIF lock detection

SPD lock	FUNCTION
0	not locked <b>or</b> non-PCM data detected
1	locked <b>and</b> PCM data detected

## 8.6.9.4 Audio sample frequency detection

A 2-bit value indicating the audio sample frequency of the IEC 60958 input signal.

**Table 22** Audio sample frequency detection

ASF1	ASF0	FUNCTION
0	0	44.1 kHz
0	1	undefined
1	0	48.0 kHz
1	1	32.0 kHz

## 8.6.9.5 PCM detection

A 1-bit value which indicates whether the IEC 60958 input contains PCM audio data or other binary data.

**Table 23** Two channel PCM input detection

PCM stat	FUNCTION
0	input with two channel PCM data
1	input without two channel PCM data

## 8.6.9.6 Pre-emphasis detection

A 1-bit value which indicates whether the pre-emphasis bit was set on the IEC 60958 input signal or not set.

**Table 24** Pre-emphasis detection

PRE	FUNCTION
0	no pre-emphasis
1	pre-emphasis

## 8.6.9.7 Clock accuracy detection

A 2-bit value indicating the timing accuracy of the IEC 60958 input signal is conforming to the IEC 60958 specification.

**Table 25** Input signal accuracy detection

ACC1	ACC0	FUNCTION
0	0	level II
0	1	level I
1	0	level III
1	1	undefined

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**9 LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{DD}$	supply voltage	note 1	2.7	5.0	V
$T_{xtal}$	crystal temperature		-25	+150	°C
$T_{stg}$	storage temperature		-65	+125	°C
$T_{amb}$	ambient temperature		-40	+85	°C
$V_{es}$	electrostatic handling voltage	Human Body Model (HBM); note 2	-2000	+2000	V
		Machine Model (MM); note 3	-200	+200	V
$I_{lu(prot)}$	latch-up protection current	$T_{amb} = 125\text{ °C}; V_{DD} = 3.6\text{ V}$		200	mA
$I_{sc(DAC)}$	DAC short-circuit current: output short-circuited to $V_{SSA(DAC)}$ output short-circuited to $V_{DDA(DAC)}$	$T_{amb} = 0\text{ °C}; V_{DD} = 3\text{ V};$ note 4		482	mA
				346	mA

**Notes**

- All  $V_{DD}$  and  $V_{SS}$  connections must be made to the same power supply.
- JEDEC class 2 compliant.
- JEDEC class B compliant, except pin  $V_{SSA(PLL)}$  which can withstand ESD pulses of -130 to +130 V.
- DAC operation cannot be guaranteed after a short-circuit has occurred.

**10 THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	85	K/W

**11 CHARACTERISTICS**

$V_{DDD} = V_{DDA} = 3.0\text{ V}$ ; IEC 60958 input with  $f_s = 48.0\text{ kHz}$ ;  $T_{amb} = 25\text{ °C}$ ;  $R_L = 5\text{ k}\Omega$ ; all voltages measured with respect to ground; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Supplies; note 1</b>						
$V_{DDA}$	analog supply voltage		2.7	3.0	3.6	V
$V_{DDA(DAC)}$	analog supply voltage for DAC		2.7	3.0	3.6	V
$V_{DDA(PLL)}$	analog supply voltage for PLL		2.7	3.0	3.6	V
$V_{DDD}$	digital supply voltage		2.7	3.0	3.6	V
$V_{DDD(C)}$	digital supply voltage for core		2.7	3.0	3.6	V
$I_{DDA(DAC)}$	analog supply current of DAC	power-on	-	8.0	-	mA
		power-down	-	750	-	$\mu\text{A}$
$I_{DDA(PLL)}$	analog supply current of PLL		-	0.7	-	mA
$I_{DDD}$	digital supply current		-	2.0	-	mA
$I_{DDD(C)}$	digital supply current of core		-	16.0	-	mA
P	power dissipation	DAC in playback mode	-	80	-	mW
		DAC in Power-down mode	-	58	-	mW

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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Digital input pins</b>						
$V_{IH}$	HIGH-level input voltage		$0.8V_{DD}$	–	$V_{DD} + 0.5$	V
$V_{IL}$	LOW-level input voltage		–0.5	–	$+0.2V_{DD}$	V
$V_{hys(RESET)}$	hysteresis voltage on pin RESET		–	0.8	–	V
$ I_{LI} $	input leakage current		–	–	10	$\mu A$
$C_i$	input capacitance		–	–	10	pF
$R_{pu(int)}$	internal pull-up resistance		16	33	78	k $\Omega$
$R_{pd(int)}$	internal pull-down resistance		16	33	78	k $\Omega$
<b>Digital output pins</b>						
$V_{OH}$	HIGH-level output voltage	$I_{OH} = -2 \text{ mA}$	$0.85V_{DD}$	–	–	V
$V_{OL}$	LOW-level output voltage	$I_{OL} = 2 \text{ mA}$	–	–	0.4	V
$I_{L(max)}$	maximum load current		–	3	–	mA
<b>Digital-to-analog converter; note 2</b>						
$V_{ref}$	reference voltage	measured with respect to $V_{SSA}$	$0.45V_{DDA}$	$0.50V_{DDA}$	$0.55V_{DDA}$	V
$V_{o(rms)}$	output voltage (RMS value)	note 3	–	900	–	mV
(THD + N)/S	total harmonic distortion-plus-noise to signal ratio	$f_i = 1.0 \text{ kHz tone}$ at 0 dB at –40 dB; A-weighted	– –	–90 –60	–85 –55	dB dB
S/N	signal-to-noise ratio	$f_i = 1.0 \text{ kHz tone}$ ; code = 0; A-weighted	95	100	–	dB
$\alpha_{cs}$	channel separation	$f_i = 1.0 \text{ kHz tone}$	–	96	–	dB
$\Delta V_o$	unbalance of output voltages	$f_i = 1.0 \text{ kHz tone}$	–	0.1	0.4	dB
<b>IEC 60958 input</b>						
$V_{i(p-p)}$	AC input voltage (peak-to-peak value)		0.2	0.5	3.3	V
$R_i$	input resistance		–	6	–	k $\Omega$
$V_{hys}$	hysteresis voltage		–	40	–	mV

**Notes**

1. All supply pins  $V_{DD}$  and  $V_{SS}$  must be connected to the same external power supply unit.
2. When the DAC must drive a higher capacitive load (above 50 pF), then a series resistor of 100  $\Omega$  must be used in order to prevent oscillations in the output stage of the operational amplifier.
3. The output voltage of the DAC is proportional to the DAC power supply voltage.

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**12 TIMING CHARACTERISTICS**

$V_{DD} = V_{DDA} = 2.7$  to  $3.6$  V;  $T_{amb} = -40$  to  $+85$  °C;  $R_L = 5$  k $\Omega$ ; all voltages measured with respect to ground; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Device reset</b>						
$t_{rst}$	reset active time		–	250	–	$\mu$ s
<b>PLL lock time</b>						
$t_{lock}$	time to lock	$f_s = 32.0$ kHz	–	97.0	–	ms
		$f_s = 44.1$ kHz	–	91.0	–	ms
		$f_s = 48.0$ kHz	–	90.0	–	ms
<b>Microcontroller L3 interface timing (see Figs 8 and 9)</b>						
$T_{cy(CLK)(L3)}$	L3CLOCK cycle time		500	–	–	ns
$t_{CLK(L3)H}$	L3CLOCK HIGH time		250	–	–	ns
$t_{CLK(L3)L}$	L3CLOCK LOW time		250	–	–	ns
$t_{su(L3)A}$	L3MODE set-up time for address mode		190	–	–	ns
$t_{h(L3)A}$	L3MODE hold time for address mode		190	–	–	ns
$t_{su(L3)D}$	L3MODE set-up time for data transfer mode		190	–	–	ns
$t_{h(L3)D}$	L3MODE hold time for data transfer mode		190	–	–	ns
$t_{(stp)(L3)}$	L3MODE stop time in data transfer mode		190	–	–	ns
$t_{su(L3)DA}$	L3DATA set-up time in address and data transfer mode		190	–	–	ns
$t_{h(L3)DA}$	L3DATA hold time in address and data transfer mode		30	–	–	ns

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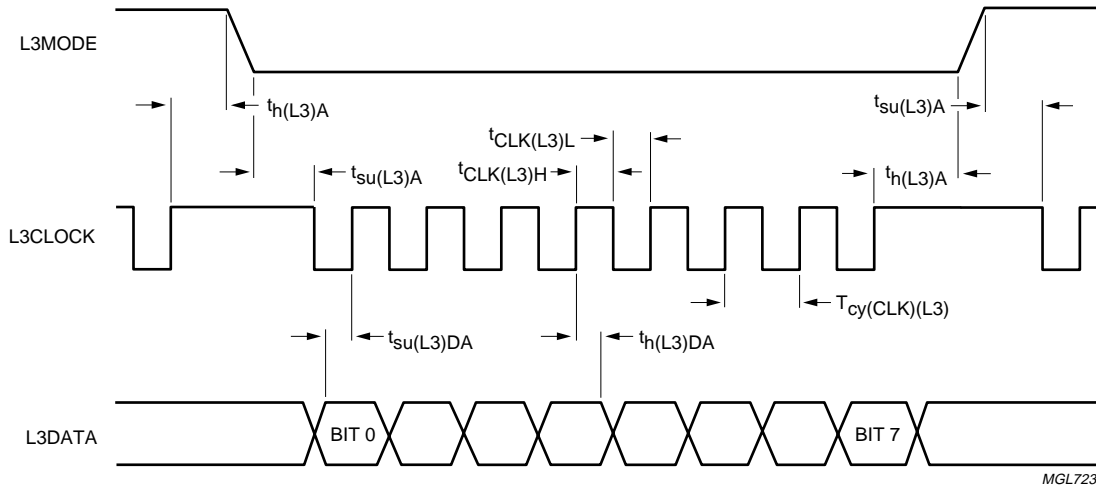


Fig.8 Timing for address mode.

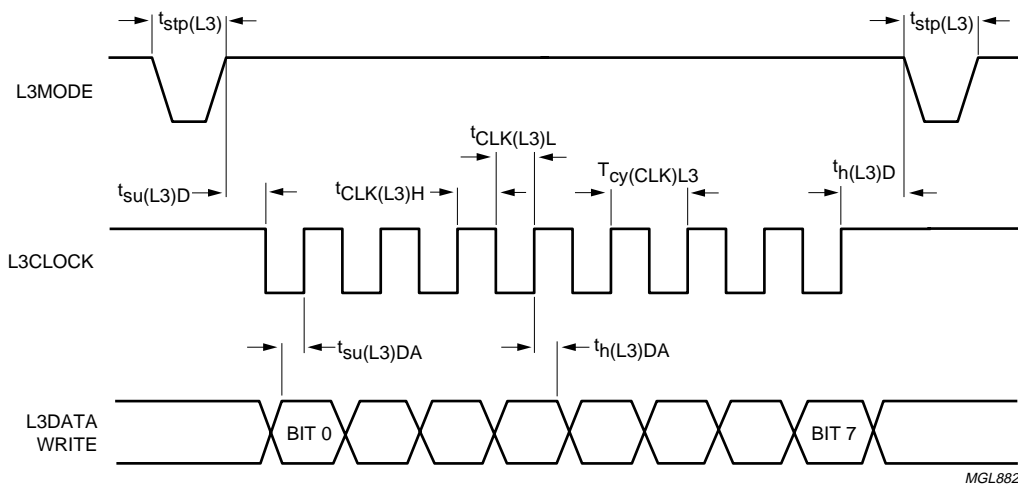


Fig.9 Timing for data transfer mode.

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## 13 APPLICATION INFORMATION

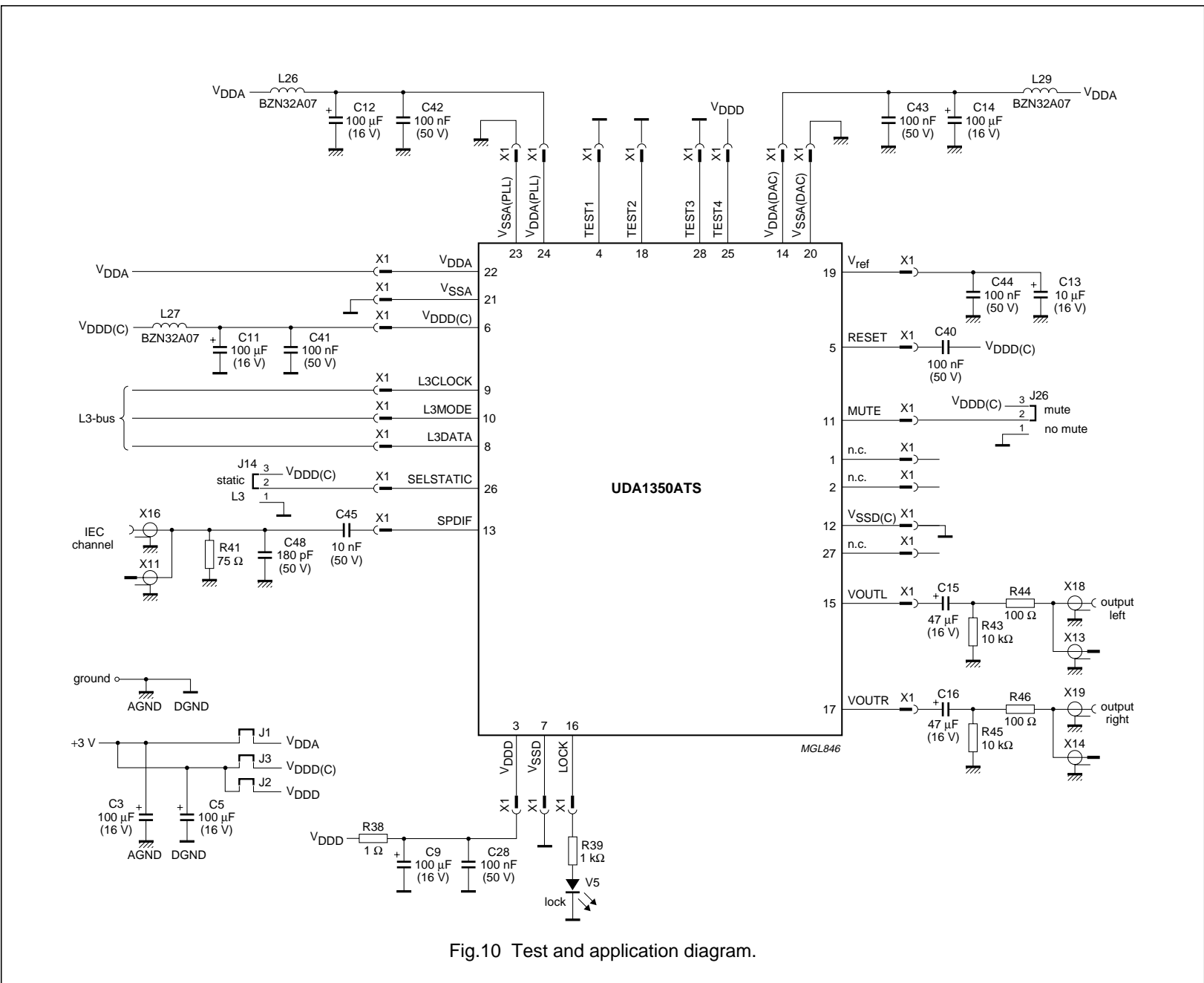


Fig.10 Test and application diagram.



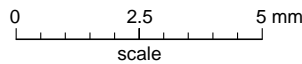
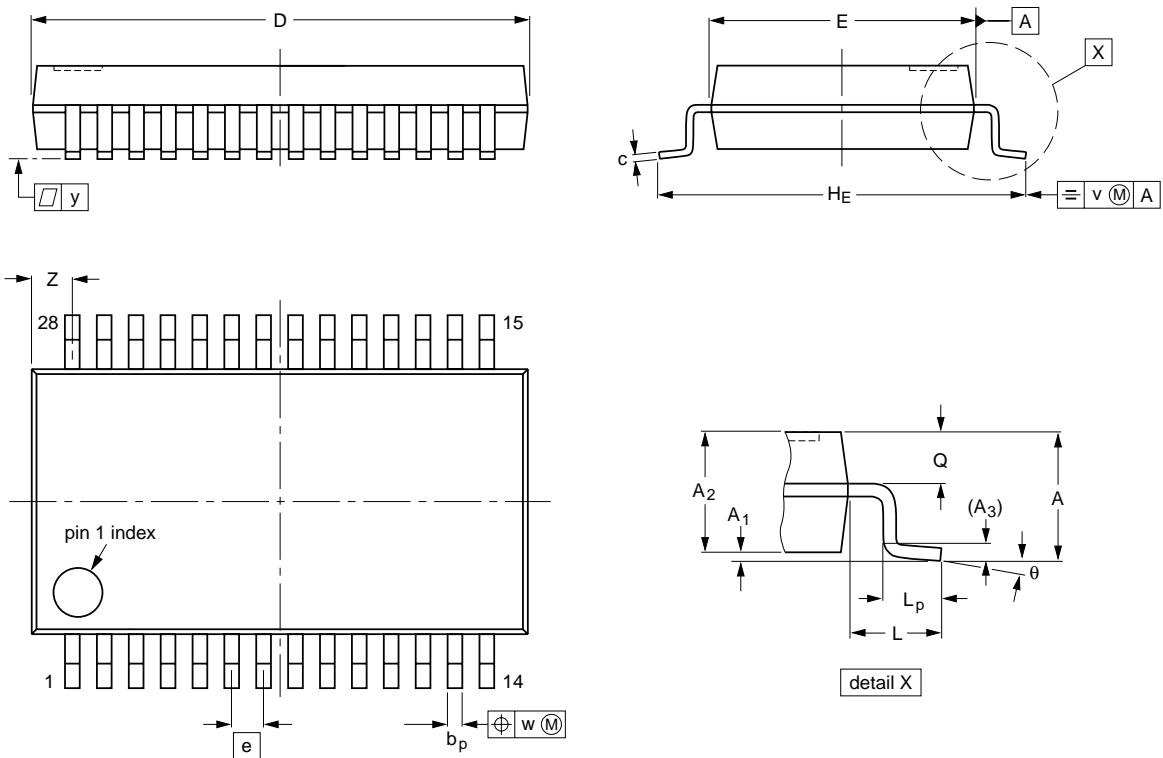
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14 PACKAGE OUTLINE

SSOP28: plastic shrink small outline package; 28 leads; body width 5.3 mm

SOT341-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	z <sup>(1)</sup>	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	10.4 10.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.1 0.7	8° 0°

Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT341-1		MO-150				95-02-04 99-12-27

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**15 SOLDERING****15.1 Introduction to soldering surface mount packages**

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"Data Handbook IC26; Integrated Circuit Packages"* (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering is not always suitable for surface mount ICs, or for printed-circuit boards with high population densities. In these situations reflow soldering is often used.

**15.2 Reflow soldering**

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, infrared/convection heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 to 250 °C. The top-surface temperature of the packages should preferably be kept below 230 °C.

**15.3 Wave soldering**

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
  - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;
  - smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

The footprint must incorporate solder thieves at the downstream end.

- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

**15.4 Manual soldering**

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

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## 15.5 Suitability of surface mount IC packages for wave and reflow soldering methods

PACKAGE	SOLDERING METHOD	
	WAVE	REFLOW <sup>(1)</sup>
BGA, SQFP	not suitable	suitable
HLQFP, HSQFP, HSOP, HTQFP, HTSSOP, SMS	not suitable <sup>(2)</sup>	suitable
PLCC <sup>(3)</sup> , SO, SOJ	suitable	suitable
LQFP, QFP, TQFP	not recommended <sup>(3)(4)</sup>	suitable
SSOP, TSSOP, VSO	not recommended <sup>(5)</sup>	suitable

**Notes**

1. All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the *"Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods"*.
2. These packages are not suitable for wave soldering as a solder joint between the printed-circuit board and heatsink (at bottom version) can not be achieved, and as solder may stick to the heatsink (on top version).
3. If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
4. Wave soldering is only suitable for LQFP, TQFP and QFP packages with a pitch (e) equal to or larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
5. Wave soldering is only suitable for SSOP and TSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.

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## 16 DATA SHEET STATUS

DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A.

## Notes

1. Please consult the most recently issued data sheet before initiating or completing a design.
2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL <http://www.semiconductors.philips.com>.

## 17 DEFINITIONS

**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

**Limiting values definition** — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

**Application information** — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

## 18 DISCLAIMERS

**Life support applications** — These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips Semiconductors customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips Semiconductors for any damages resulting from such application.

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**NOTES**

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**NOTES**

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